

EL465854327US

Inventor: Shozo Nagano et al.

Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, Metal Alloys For Use As a Conductive Interconnection In An Integrated Circuit, And Physical Vapor Deposition Targets

Assignee: Micron Technology, Inc.

SAH  
#3  
7-6-01

JC868 U.S. PTO  
09/784234  
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**INFORMATION DISCLOSURE STATEMENT**

**PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98**

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449.

No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a divisional application of co-pending application Serial No. 09/449,025, filed November 4, 1999. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 2-13-01

By:   
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